

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) An optoelectronic component ~~[[1]]~~ comprising a housing body ~~[[2]]~~ and at least one semiconductor chip ~~[[8]]~~ disposed thereon, said housing body having a base part ~~[[13]]~~ comprising a connector body ~~[[16]]~~, on which a connecting conductor material ~~[[6, 7]]~~ is disposed, and having a reflector part ~~[[14]]~~ comprising a reflector body ~~[[23]]~~, on which a reflector material ~~[[9]]~~ is disposed, ~~characterized in that~~ wherein said connector body and said reflector body are preformed separately from each other and said reflector body is disposed on said connector body in the form of a reflector top.
2. (Currently Amended) The optoelectronic component as in claim 1, ~~characterized in that~~ wherein said base part and said reflector part are preformed separately from each other.
3. (Currently Amended) The optoelectronic component as in claim 1 ~~[[or 2]]~~, ~~characterized in that~~ wherein said housing body contains a ceramic.
4. (Currently Amended) The optoelectronic component as in ~~one of the preceding claims~~ claim 1, ~~characterized in that~~ wherein said housing body contains aluminum nitride or aluminum oxide.
5. (Currently Amended) The optoelectronic component as in ~~one of the preceding claims~~ claim 1, ~~characterized in that~~ wherein said connecting conductor material is different from said reflector material.

6. (Currently Amended) The optoelectronic component as in ~~one of the preceding~~ claims claim 1, ~~characterized in that~~ wherein said connecting conductor material contains a metal.

7. (Currently Amended) The optoelectronic component as in ~~one of the preceding~~ claims claim 1, ~~characterized in that~~ wherein said reflector material contains a metal.

8. (Currently Amended) The optoelectronic component as in ~~one of the preceding~~ claims claim 1, ~~characterized in that~~ wherein said connecting conductor material contains Au and said reflector material Ag.

9. (Currently Amended) The optoelectronic component as in ~~one of the preceding~~ claims claim 1, ~~characterized in that~~ wherein said housing body has a cavity [(3)] in which said semiconductor chip is disposed.

10. (Currently Amended) The optoelectronic component as in ~~one of the preceding~~ claims claim 1, ~~characterized in that~~ wherein said reflector body is provided with a recess [(30)], said recess is part of the cavity of the housing body and said reflector material is disposed on a wall [(5)] of said recess.

11. (Currently Amended) The optoelectronic component as in ~~one of the preceding~~ claims claim 1, ~~characterized in that~~ wherein said reflector material is electrically insulated from said connecting conductor material.

12. (Currently Amended) The optoelectronic component as in ~~one of the preceding~~ claims claim 1, wherein an insulation part [(15)] is disposed between said base part and said reflector part.

13. (Currently Amended) The optoelectronic component as in claim 12, ~~characterized in that~~ wherein said insulation part is preformed separately from said base part and said reflector part.

14. (Currently Amended) The optoelectronic component as in ~~one of the preceding claims~~ claim 1, ~~characterized in that~~ wherein disposed on said base part, particularly after said reflector part, is an adhesion promoting part $[(24)]$ provided with a recess that is part of the cavity of said housing body.

15. (Currently Amended) The optoelectronic component as in claim 14, ~~characterized in that~~ wherein disposed in the cavity of said housing body is an envelope $[(10)]$ that at least partially envelops said semiconductor chip.

16. (Currently Amended) The optoelectronic component as in ~~one of the preceding claims~~ claim 1, ~~characterized in that~~ wherein said envelope is arranged at said adhesion promoting part and said envelope adheres better to said adhesion promoting part than it does to said reflector material.

17. (Currently Amended) The optoelectronic component as in ~~one of the preceding claims~~ claim 1, ~~characterized in that~~ wherein said base part includes a heat sink $[(22)]$.

18. (Currently Amended) The optoelectronic component as in claim 17, ~~characterized in that~~ wherein said heat sink is electrically insulated from said semiconductor chip.

19. (New) The optoelectronic component as in claim 2, wherein said housing body contains a ceramic.